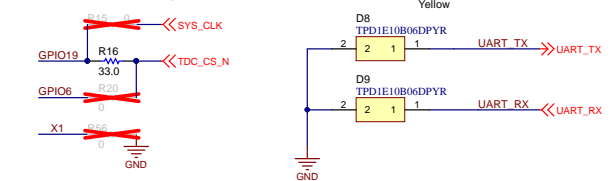


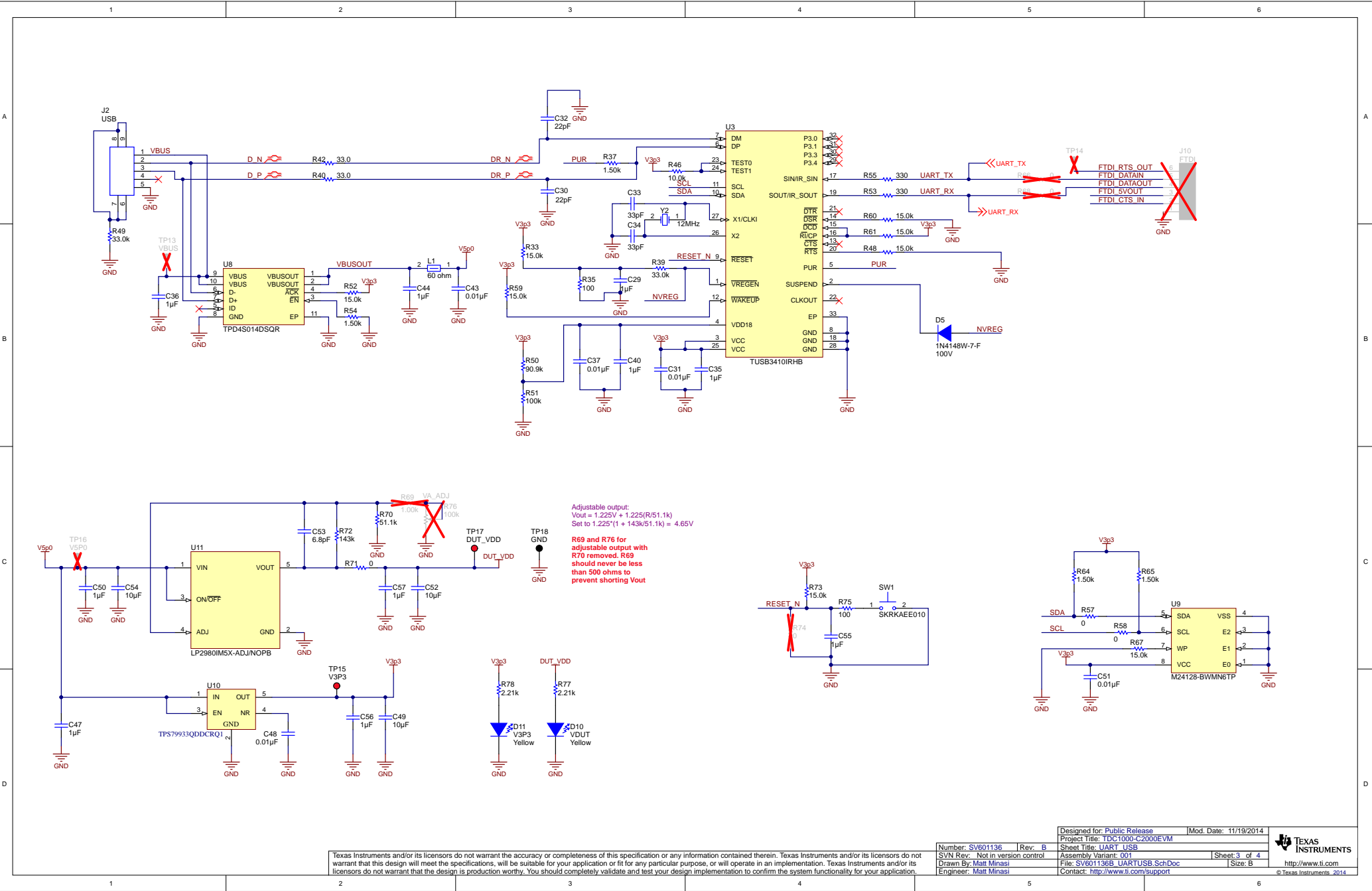
Default EVM configuration: Two crystals
For single crystal configuration:
Populate R15, R20 and R56
Do not populate R16 and R84
Custom firmware is required



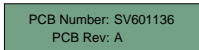
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Number: SV601136	Rev: B	Designed for Public Release	Mod. Date: 11/19/2014
SVN Rev: Not in version control	Assembly Variant: 001	Project Title: TDC1000-C2000EVM	Sheet Title: Processor
Drawn By: Matt Minasi	File: SV601136B_C2000.SchDoc	Project Title: TDC1000-C2000EVM	Sheet: 2 of 4
Engineer: Matt Minasi	Contact: http://www.ti.com/support	Project Title: TDC1000-C2000EVM	Size: B





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Label Table	
Variant	Label Text
001	TDC1000-C2000EVM

Size: 0.65" x 0.20"

This Assembly Note is for PCB labels only

These assemblies are ESD sensitive, ESD precautions shall be observed.

These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

These assemblies must comply with workmanship standards IPC-A-610 Class 2., unless otherwise specified.

Controlled Impedance Layers: 2. Top and bottom layers 50 ohm impedance +/- 5% for 8 mil traces.

Place SH-JP1 in position 1-2 of JP1